



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-C164CI-8EM DB		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA001053054							
<b>Package</b>		PG-MQFP-80-7		<b>Weight*</b>		980.61 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	52.594	5.36	5.36	53634	53634	
leadframe	non noble metal	magnesium	7439-95-4	0.349	0.04		356		
	inorganic material	silicon	7440-21-3	1.511	0.15		1541		
	non noble metal	nickel	7440-02-0	6.975	0.71		7113		
	non noble metal	copper	7440-50-8	223.668	22.81	23.71	228090	237100	
wire	noble metal	gold	7440-57-5	3.387	0.35	0.35	3454	3454	
encapsulation	organic material	carbon black	1333-86-4	2.011	0.21		2051		
	plastics	epoxy resin	-	85.137	8.68		86820		
	inorganic material	silicondioxide	60676-86-0	583.220	59.47	68.36	594751	683622	
leadfinish	non noble metal	tin	7440-31-5	9.487	0.97	0.97	9675	9675	
plating	noble metal	silver	7440-22-4	3.927	0.40	0.40	4005	4005	
glue	plastics	acrylic resin	-	1.669	0.17		1702		
	noble metal	silver	7440-22-4	6.676	0.68	0.85	6808	8510	
*deviation	< 10%					Sum in total:	100,00		1000000

### Important Remarks:

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